

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
XUE-YUAN XIAO	03/27/2015
JIA-WEI GU	03/27/2015
ZHANG-LAN XUE	03/27/2015
ZI-QIANG ZHU	03/27/2015
RECEIVING PARTY DATA	
Name:	FOXCONN INTERCONNECT TECHNOLOGY LIMITED
Street Address:	Floor 4, Willow House, Cricket Square, P O Box 2804
City:	Grand Cayman
State/Country:	CAYMAN ISLANDS
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	14675605
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SIGNATURE:	/WEI TE CHUNG/
DATE SIGNED:	03/31/2015
Total Attachments: 2	
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ASSIGNMENT

In consideration of value received, the receipt and sufficiency of which are hereby acknowledged, the undersigned ASSIGNOR(S)

- 1. XUE-YUAN XIAO , residing at Kunshan, China
- 2. JIA-WEI GU , residing at Kunshan, China
- 3. ZHANG-LAN XUE , residing at Kunshan, China
- 4. ZI-QIANG ZHU , residing at Kunshan, China
- 5. _____ , residing at _____
- 6. _____ , residing at _____
- 7. _____ , residing at _____
- 8. _____ , residing at _____

hereby sell(s), assign(s) and transfer(s) unto: **FOXCONN INTERCONNECT TECHNOLOGY LIMITED** having a principal place of business at **Floor 4, Willow House, Cricket Square, P O Box 2804, Grand Cayman KY1-1112 , Cayman Islands**, hereafter designated "ASSIGNEE" the entire right, title and interest for the United States of America as defined in 35 U.S.C. 100, in the invention and all patent applications including any and all divisions, continuations, substitutes, and reissues thereof, and all resulting patents, known as **SIGNAL TRANSMISSION MODULE WITH RELIABLE SEALING STRUCTURE** for which the undersigned

[] previously executed --- Ser. No. _____ and filing date of _____
[x] is executing concurrently herewith

an application for Letters Patent of United States of America

AND the undersigned hereby authorize(s) and request(s) the United States Commissioner of Patents and Trademarks to issue said Letters Patent to the said ASSIGNEE, for its interest as ASSIGNEE, its successors, assigns and legal representatives; the undersigned agree(s) that the attorneys of record in said application, if any, shall hereafter act on behalf of said ASSIGNEE;

AND the undersigned hereby agree(s) to testify and execute any papers for ASSIGNEE, its successors, assigns and legal representatives, deemed essential by ASSIGNEE to ASSIGNEE's full protection and title in and to the invention hereby transferred.

